

## HIGH-SPEED 4K x 9DUAL-PORT STATIC RAM

IDT7014S

#### **Features:**

- True Dual-Ported memory cells which allow simultaneous reads of the same memory location
- High-speed access
  - Commercial: 12/15/20/25ns (max.)
  - Industrial: 15/20/25ns (max.)
- Standard-power operation
  - IDT7014S
    - Active: 750mW (typ.)
- Fully asynchronous operation from either port
- TTL-compatible; single 5V (±10%) power supply
- Available in 52-pin PLCC and a 64-pin TQFP
- Industrial temperature range (-40°C to +85°C) is available for selected speeds

### **Description:**

The IDT7014 is a high-speed 4K x 9 Dual-Port Static RAM designed to be used in systems where on-chip hardware port arbitration is not needed. This part lends itself to high-speed applications which do not rely on BUSY signals to manage simultaneous access.

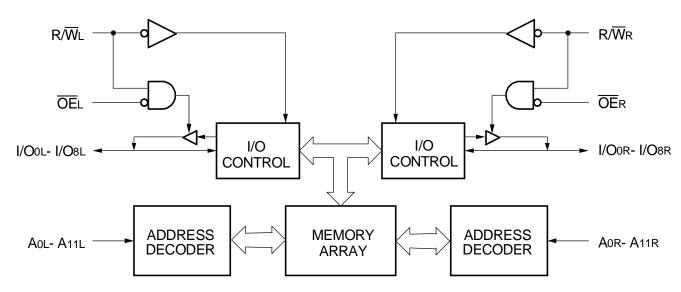
The IDT7014 provides two independent ports with separate control, address, and I/O pins that permit independent, asynchronous access for reads or writes to any location in memory. See functional description.

The IDT7014 utilitizes a 9-bit wide data path to allow for parity at the user's option. This feature is especially useful in data communication applications where it is necessary to use a parity bit for transmission/reception error checking.

Fabricated using IDT's high-performance technology, these Dual-Portstypically operate on only 750mW of power at maximum access times as fast as 12ns.

The IDT7014 is packaged in a 52-pin PLCC and a 64-pin thin quad flatpack, (TQFP).

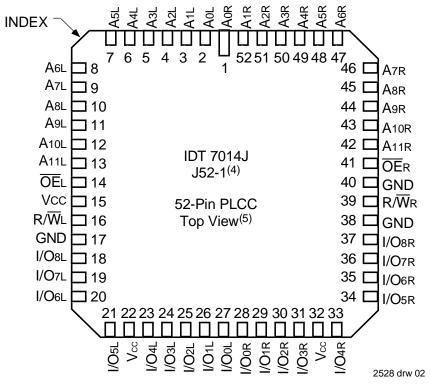
## **Functional Block Diagram**

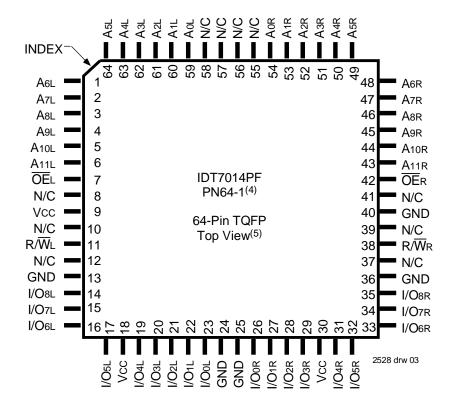


2528 drw 01

**MARCH 2000** 

## Pin Configuration(1,2,3)





#### NOTES:

- 1. All Vcc pins must be connected to power supply.
- 2. All GND pins must be connected to ground supply.
- 3. J52-1 package body is approximately .75 in x .75 in. x .17 in. PN64-1 package body is approximately 14mm x 14mm x 1.4mm.
- 4. This package code is used to reference the package diagram.
- 5. This text does not indicate the orientation of the actual part-marking

## **Absolute Maximum Ratings** (1)

Symbol	Rating	Commercial & Industrial	Unit
VTERM <sup>(2)</sup>	Terminal Voltage with Respect to GND	-0.5 to +7.0	V
VTERM <sup>(2)</sup>	Terminal Voltage	-0.5 to +Vcc	V
TBIAS	Temperature Under Bias	-55 to +125	°C
Tstg	Storage Temperature	-55 to +125	°C
ЮИТ	DC Output Current	50	mA

#### NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- VTERM must not exceed Vcc + 10% for more than 25% of the cycle time or 10ns maximum, and is limited to ≤ 20mA for the period of VTERM ≥ Vcc + 10%.

# Maximum Operating Temperature and Supply Voltage (1,2)

Grade	Ambient Temperature	GND	Vcc
Commercial	0°C to +70°C	0V	5.0V <u>+</u> 10%
Industrial	-40°C to +85°C	0V	5.0V <u>+</u> 10%

#### NOTES:

2528 tbl 01

1. This is the parameter Ta.

# Recommended DC Operating Conditions

Symbol	Parameter	Min.	Тур.	Max.	Unit
Vcc	Supply Voltage	4.5	5.0	5.5	٧
GND	Ground	0	0	0	٧
VIH	Input High Voltage	2.2	_	6.0(2)	٧
VIL	Input Low Voltage	-0.5 <sup>(1)</sup>		0.8	٧

#### NOTES

- 1. VIL  $\geq$  -1.5V for pulse width less than 10ns.
- 2. VTERM must not exceed Vcc + 10%.

# DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range<sup>(1)</sup> (Vcc = $5.0V \pm 10\%$ )

			7014S		
Symbol	Parameter	Test Conditions	Min.	Max.	Unit
LI	Input Leakage Current	Vcc = 5.5V, $VIN = 0V$ to $Vcc$	-	10	μA
ILO	Output Leakage Current	Vout = 0V to Vcc	_	10	μA
Vol	Output Low Voltage	IoL = +4mA	_	0.4	V
Voh	Output High Voltage	Iон = -4mA	2.4	_	V

#### NOTE:

1. At  $Vcc \le 2.0V$  input leakages are undefined.

2528 thl 0.4

2528 tbl 02

# DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range (Vcc = 5V ± 10%)

_					4S12 I Only		4S15 & Ind	
Symbol	Parameter	Test Condition	Version	Тур.	Max	Тур.	Max	Unit
Icc	Dynamic Operating	Outputs Open f = f <sub>MAX</sub> <sup>(1)</sup>	COM'L S	160	250	160	250	mA
	Current (Both Ports Active)	I = IMAX''	IND S	_	_	160	260	

2528 tbl 05a

						1S20 & Ind		4S25 & Ind	
Symbol	Parameter	Test Condition	Version	1	Тур.	Max	Тур.	Max.	Unit
Icc	Dynamic Operating	Outputs Open f = f <sub>MAX</sub> <sup>(1)</sup>	COM'L	S	155	245	150	240	mA
	Current (Both Ports Active)	I = IMAX	IND	S	155	260	150	255	

2528 tbl 05b

#### NOTES:

1. At f = fmax, address inputs are cycling at the maximum read cycle of 1/tRC using the "AC Test Conditions" input levels of GND to 3V.

### **AC Test Conditions**

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	3ns Max.
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	Figures 1,2 and 3

2528 tbl 06

2528 tbl 07

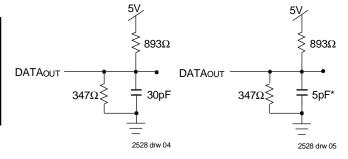


Figure 1. AC Output Test Load.

Figure 2. Output Test Load (for thz, twz, and tow) \*Including scope and jiq.

# Capacitance<sup>(1)</sup>

### (Ta = +25°C, f = 1.0MHz) TQFP Package Only

Symbol	Parameter	Conditions <sup>(2)</sup>	Max.	Unit
CIN	Input Capacitance	VIN = 3dV	9	pF
Соит	Output Capacitance	Vout = 3dV	10	pF

#### NOTES:

- This parameter is determined by device characteristics but is not production tested.
- 3dv references the interpolated capacitance when the input and output signals swith from 0V to 3V or from 3V to 0V.

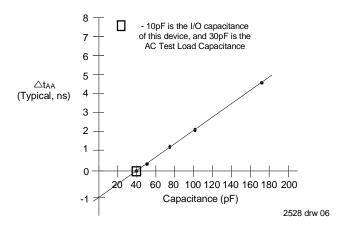


Figure 3. Typical Output Derating (Lumped Capacitive Load).

## AC Electrical Characteristics Over the Operating Temperature and Supply Voltage

		7014S12 Com'l Only		7014S15 Com'l & Ind		
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit
READ CYCLE						
trc	Read Cycle Time	12	1	15	-	ns
taa	Address Access Time	_	12	I	15	ns
taoe	Output Enable Access Time	_	8	I	8	ns
tон	Output Hold from Address Change	3	1	3	-	ns
tLz	Output Low-Z Time <sup>(1,2)</sup>	3	-	3	-	ns
tHZ	Output High-Z Time <sup>(1,2)</sup>	_	7		7	ns

2528 tbl 08a

		7014S20 Com'l & Ind		7014S25 Com'l & Ind		
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit
READ CYCLE						
trc	Read Cycle Time	20		25	-	ns
taa	Address Access Time	_	20	I	25	ns
taoe	Output Enable Access Time	_	10	I	12	ns
tон	Output Hold from Address Change	3		3	-	ns
tlz	Output Low-Z Time <sup>(1,2)</sup>	3		3	1	ns
tHZ	Output High-Z Time <sup>(1,2)</sup>		9	_	11	ns

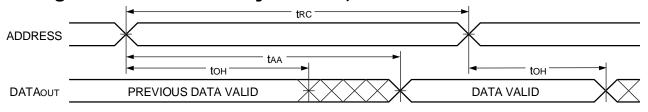
#### NOTES

2528 tbl 08b

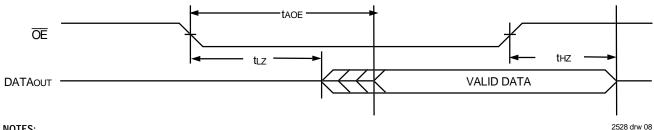
- 1. Transition is measured 0mV from Low or High-impedance voltage with Output Test Load (Figure 2).
- 2. This parameter is determined by device characterization, but is not production tested.

2528 drw 07

## Timing Waveform of Read Cycle No. 1, Either Side<sup>(1,2)</sup>



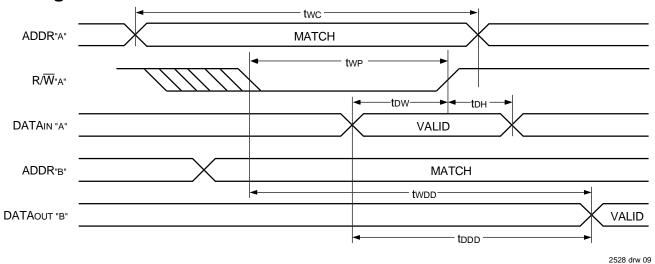
## Timing Waveform of Read Cycle No. 2, Either Side<sup>(1, 3)</sup>



#### NOTES:

- 1.  $R/\overline{W} = VIH$  for Read Cycles.
- 2.  $\overline{OE} = VIL$ .
- 3. Addresses valid prior to  $\overline{\text{OE}}$  transition LOW.

## Timing Waveform of Write with Port-to-Port Read(1,2)



#### NOTES:

- 1.  $R/\overline{W}^*B^* = V_{IH}$ , read cycle pass through.
- 2. All timing is the same for left and right ports. Port "A" may be either left or right port. Port "B" is opposite from port "A".

## AC Electrical Characteristics Over the Operating Temperature and Supply Voltage

		7014S12 Com'l Only		7014S15 Com'l & Ind			
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit	
WRITE CYCLE							
twc	Write Cycle Time	12	_	15	_	ns	
taw	Address Valid to End-of-Write	10	_	14	_	ns	
tas	Address Set-up Time	0	_	0		ns	
twp	Write Pulse Width	10	_	12	_	ns	
twr	Write Recovery Time	1	_	1	_	ns	
tow	Data Valid to End-of-Write	8	_	10		ns	
tHZ	Output High-Z Time <sup>(1,2)</sup>	_	7	_	7	ns	
toн	Data Hold Time <sup>(3)</sup>	0	_	0	_	ns	
twz	Write Enable to Output in High-Z <sup>(1,2)</sup>	_	7	_	7	ns	
tow	Output Active from End-of-Write <sup>(1,2,3)</sup>	0	_	0		ns	
twdd	Write Pulse to Data Delay <sup>(4)</sup>	_	25	_	30	ns	
todd	Write Data Valid to Read Data Delay (4)	_	22	_	25	ns	

2528 tbl 09a

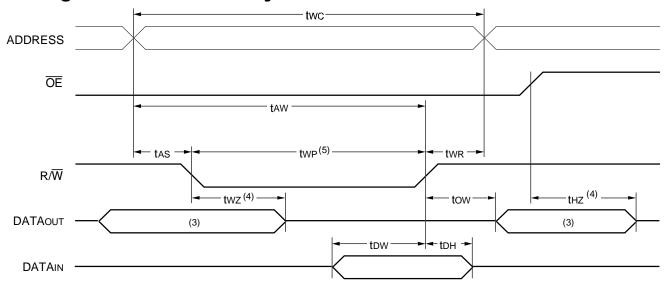
		7014S20 Com'l & Ind		7014S25 Com'l & Ind		
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit
WRITE CYCLE						
twc	Write Cycle Time	20		25	_	ns
taw	Address Valid to End-of-Write	15		20	_	ns
tas	Address Set-up Time	0		0	_	ns
twp	Write Pulse Width	15		20	_	ns
twr	Write Recovery Time	2		2	_	ns
tow	Data Valid to End-of-Write	12		15	_	ns
tHZ	Output High-Z Time <sup>(1,2)</sup>	_	9		11	ns
toн	Data Hold Time <sup>(3)</sup>	0		0	_	ns
twz	Write Enable to Output in High-Z <sup>(1,2)</sup>	_	9	_	11	ns
tow	Output Active from End-of-Write (1,2,3)	0		0	_	ns
twdd	Write Pulse to Data Delay <sup>(4)</sup>		40	_	45	ns
todd	Write Data Valid to Read Data Delay <sup>(4)</sup>	_	30	_	35	ns

#### NOTES

2528 tbl 09b

- 1. Transition is measured 0mV from Low or High-impedance voltage with Output Test Load (Figure 2).
- 2. This parameter is guaranteed by device characterization, but is not production tested.
- 3. The specification for tDH must be met by the device supplying write data to the RAM under all operating conditions. Although tDH and tow values will vary over voltage and temperature, the actual tDH will always be smaller than the actual tow.
- 4. Port-to-port delay through RAM cells from writing port to reading port, refer to "Timing Waveform of Write With Port-to-Port Read".

# Timing Waveform of Write Cycle<sup>(1,2,3,4,5)</sup>



NOTES:

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- 1.  $R/\overline{W}$  must be HIGH during all address transitions.
- 2. two is measured from  $R/\overline{W}$  going HIGH to the end of write cycle.
- 3. During this period, the I/O pins are in the output state, and input signals must not be applied.
- 4. Transition is measured 0mV from the Low or High-impedance voltage with the Output Test Load (Figure 2).
- 5. If  $\overline{OE}$  is LOW during a R/ $\overline{W}$  controlled write cycle, the write pulse width must be the larger of twp or (twz + tbw) to allow the I/O drivers to turn off data to be placed on the bus for the required tbw. If  $\overline{OE}$  is HIGH during an R/ $\overline{W}$  controlled write cycle, this requirement does not apply and the write pulse can be as short as the specified twp.

## **Functional Description**

The IDT7014 provides two ports with separate control, address, and I/O pins that permit independent access for reads or writes to any location in memory. It lacks the chip enable feature of CMOS Dual Ports, thus it operates in active mode as soon as power is applied. Each port has its own Output Enable control ( $\overline{\text{OE}}$ ). In the read mode, the port's  $\overline{\text{OE}}$  turns on the output drivers when set LOW. The user application should avoid simultaneous write operations to the same memory location. There is no on-chip arbitration circuitry to resolve write priority and partial data from both ports may be written. READ/WRITE conditions are illustrated in Table 1.

## **Truth Table I - Read/Write Control**

Left or Right Port <sup>(1)</sup>			
R∕W	ŌĒ	D <sub>0</sub> -8	Function
L	Х	DATAIN	Data written into memory
Н	L	DATAOUT	Data in memory output on port
Х	Н	Z	High-impedance outputs

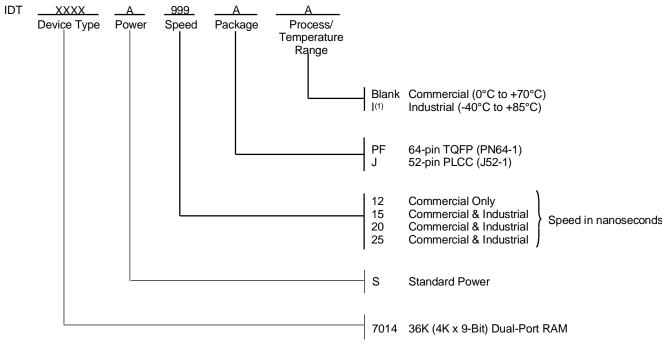
NOTE:

2528 tbl 10

1. AoL - A11L is not equal to AoR - A11R.

'H' = HIGH,'L' = LOW, 'X' = Don't Care, and 'Z' = HIGH Impedance.

## **Ordering Information**



2528 drw 11

## **Datasheet Document History**

1/6/99: Initiated datasheet document history

Converted to new format

Cosmetic and typographical corrections

Page 2 Added additional notes to pin configurations

6/3/99: Changed drawing format

Page 1 Corrected DSC number

3/10/00: Added Industrial Temperature Ranges and deleted corresponding notes

Replaced IDT logo

Page 1 Made corrections to drawing Changed ±200mV to 0mV in notes Page 6 made changes to drawings



#### **CORPORATE HEADQUARTERS**

2975 Stender Way Santa Clara, CA 95054

#### for SALES:

800-345-7015 or 408-727-6116 fax: 408-492-8674 www.idt.com

for Tech Support: 831-754-4613 DualPortHelp@idt.com

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